

Electronic Patent Application Fee Transmittal

Application Number:	10585461			
Filing Date:	27-May-2009			
Title of Invention:	Circuit connection material, film-shaped circuit connection material using the same, circuit member connection structure, and manufacturing method thereof			
First Named Inventor/Applicant Name:	Jun Taketatsu			
Filer:	William Ivan Solomon/Kelli Harris			
Attorney Docket Number:	1303.46354X00			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1615	2	60	120
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 2 months with \$0 paid	1252	1	560	560
Miscellaneous:				
Total in USD (\$)				680